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# INTERCONNECT TECHNOLOGY FOR THREE-DIMENSIONAL CHIP INTEGRATION



Cuvillier Verlag Okt 2007, 2007. Taschenbuch. Condition: Neu. Neuware - 3D-integration, or vertical chip integration, is a technology that aims to shorten the interconnect path between integrated circuits and to increase the interconnect density by using through-chip micro vias. It allows a smaller circuit footprint by chip-stacking and can combine a variety of technologies. This thesis treats the technological aspects of a novel 3D-integration concept, which is based on processes that follow the sequence: wafer thinning, via processing, chip stacking...

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